

Differential Imaging Microscopy of Physically and Chemically Complex Surfaces Relevant to Materials Surveillance

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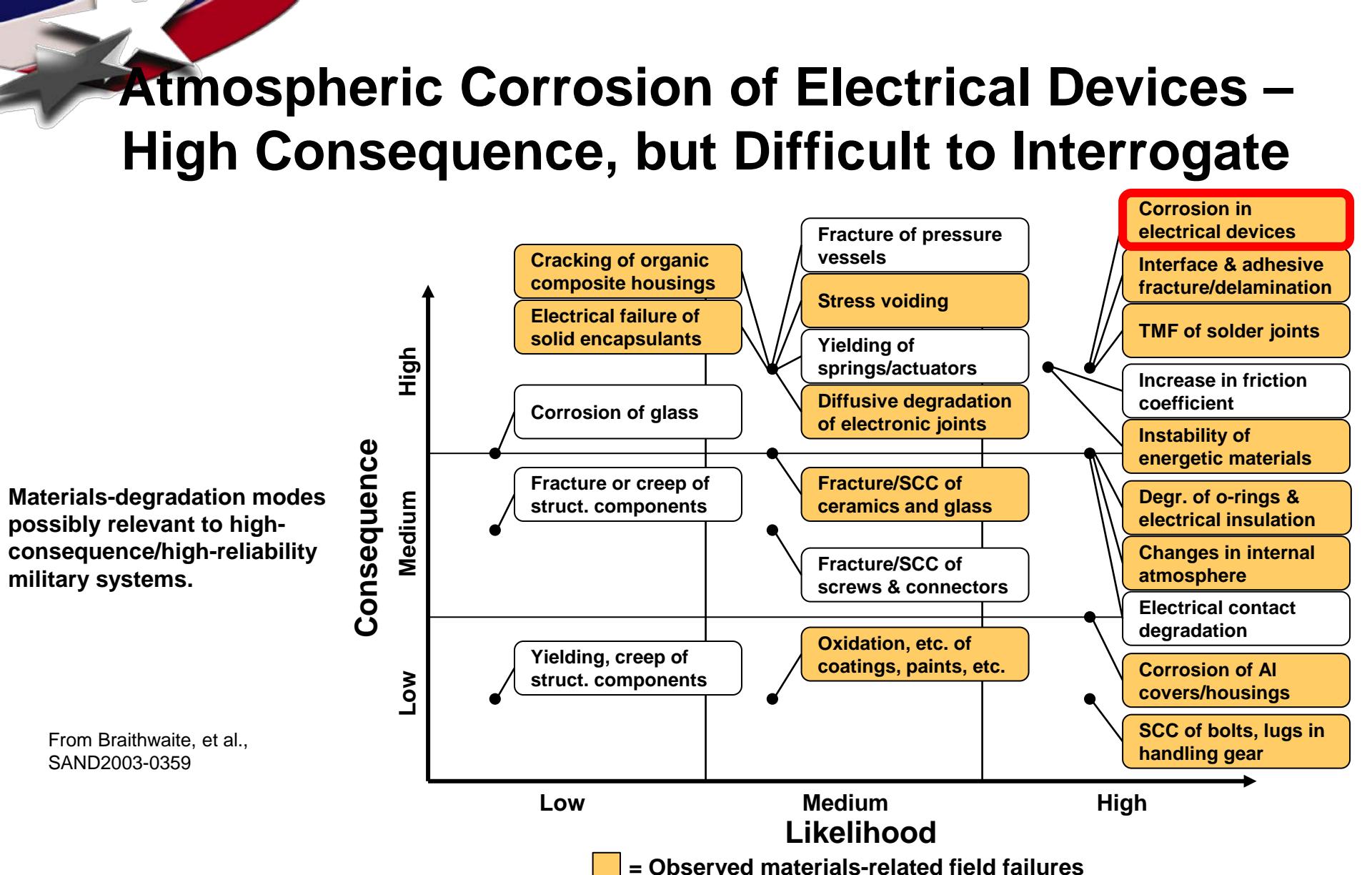
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Atmospheric Corrosion of Electrical Devices – High Consequence, but Difficult to Interrogate



- Atmospheric corrosion processes can not be assessed via electrochemical techniques
- An optical technique is needed to overcome this issue

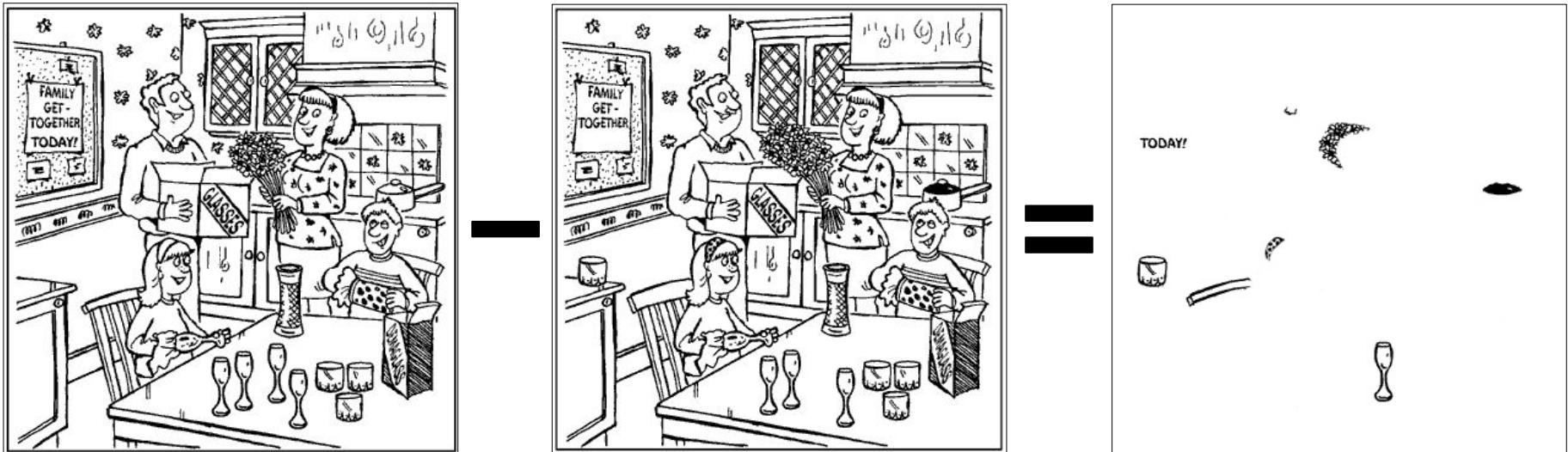


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What is Differential Imaging?

- Subtraction of an image taken at time t from an image taken at time $t+\Delta t$
 - Eliminate portions of the image which do not change
 - Resultant image nominally contains only those aspects which have changed
 - Can be applied to any imaging technique – not just optical



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Background

- **Differential imaging technique for in-situ observation of atmospheric corrosion**
 - Similar to work of Huang, et. al (2006) for aqueous samples
 - System consists of imaging hardware/optics and an exposure chamber, along with data acquisition and image analysis software
- **Demonstration of system capabilities performed on noble metal plated copper specimens, simulating metallurgies commonly used in microelectronic connectors**



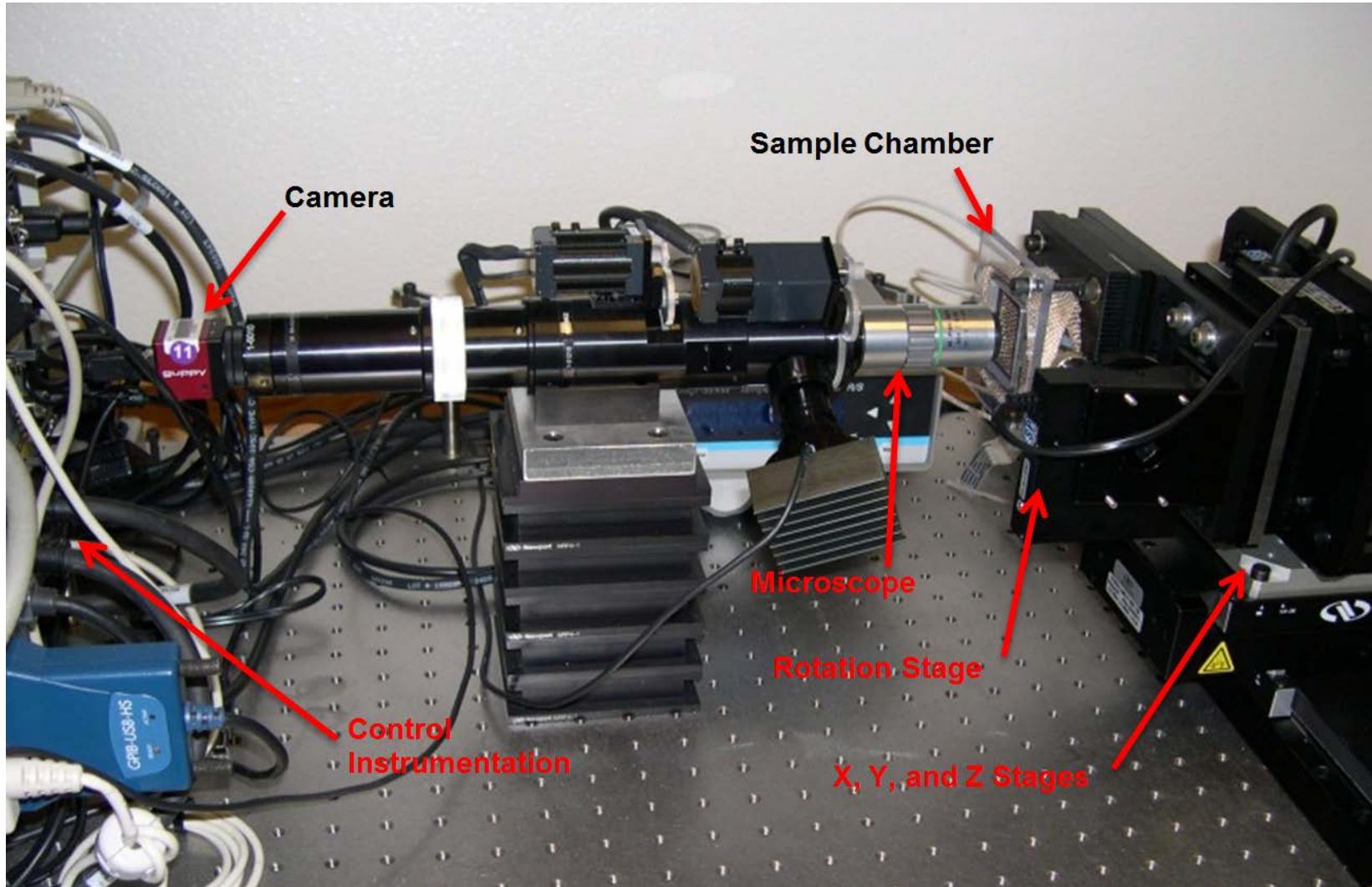
System Configuration

- **Goal: develop a system capable of monitoring a corroding surface in-situ**
 - Must be non-destructive
 - Need to be able to map a surface
 - Need to have flexibility in terms of the specimen geometry and environmental conditions
- **Basic system components**
 - Image acquisition system (resolution, repeatability, reliability)
 - Sample positioning/manipulation (repeatability, reliability)
 - Atmospheric control/exposure system
 - Control software to bring it all together and do image manipulation (subtraction, stitching, mapping)





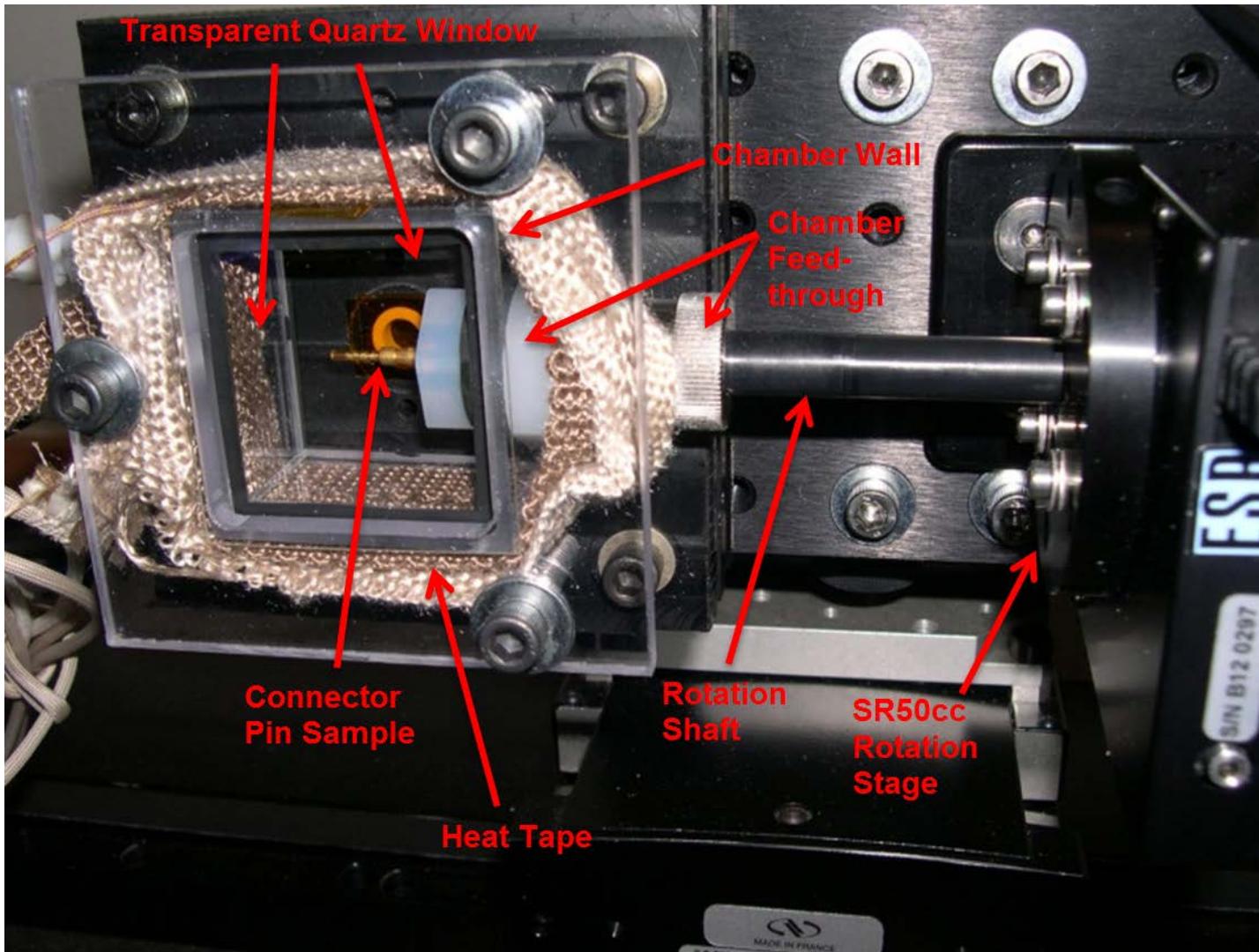
Overall System Configuration



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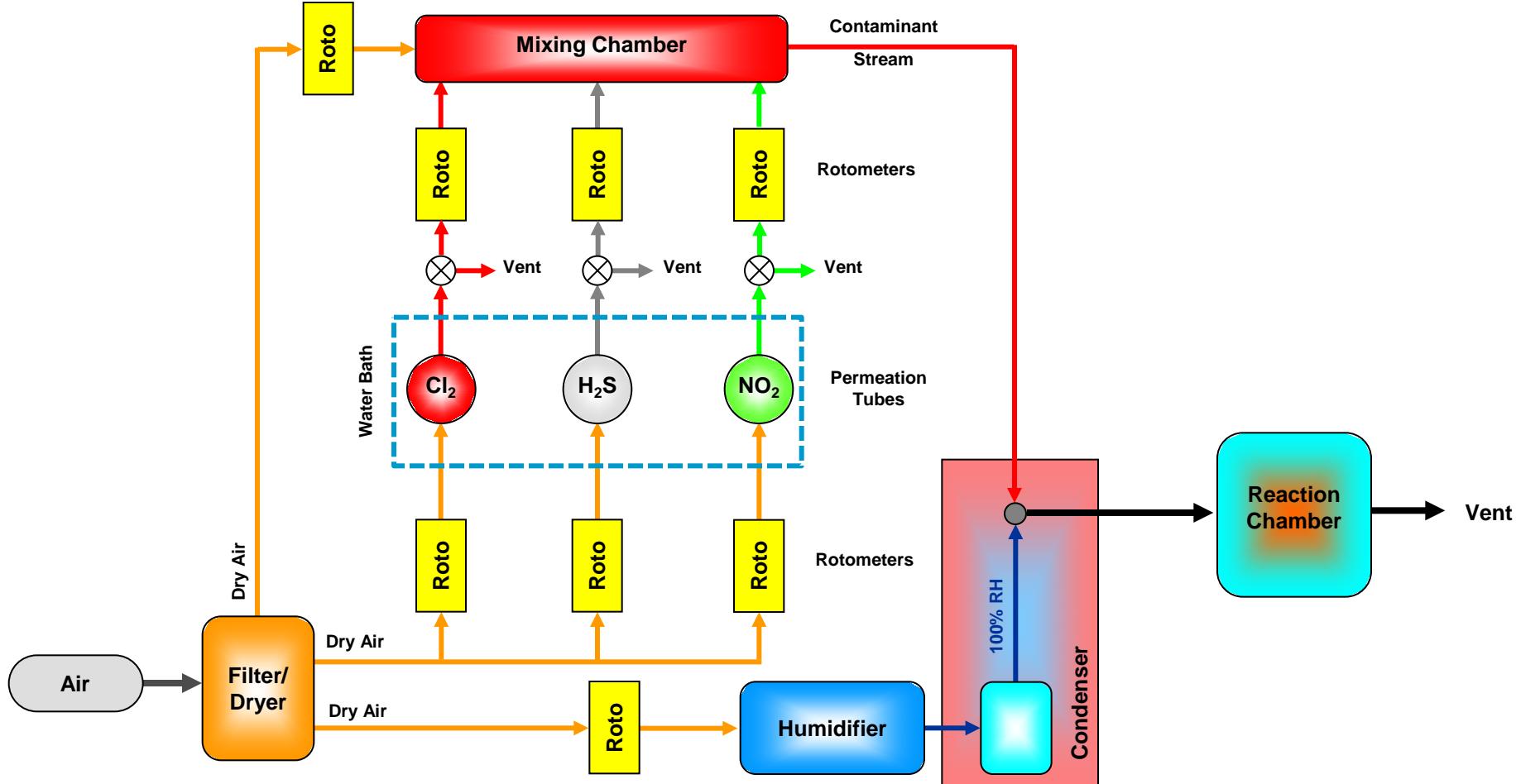
The Exposure Chamber (One Example)



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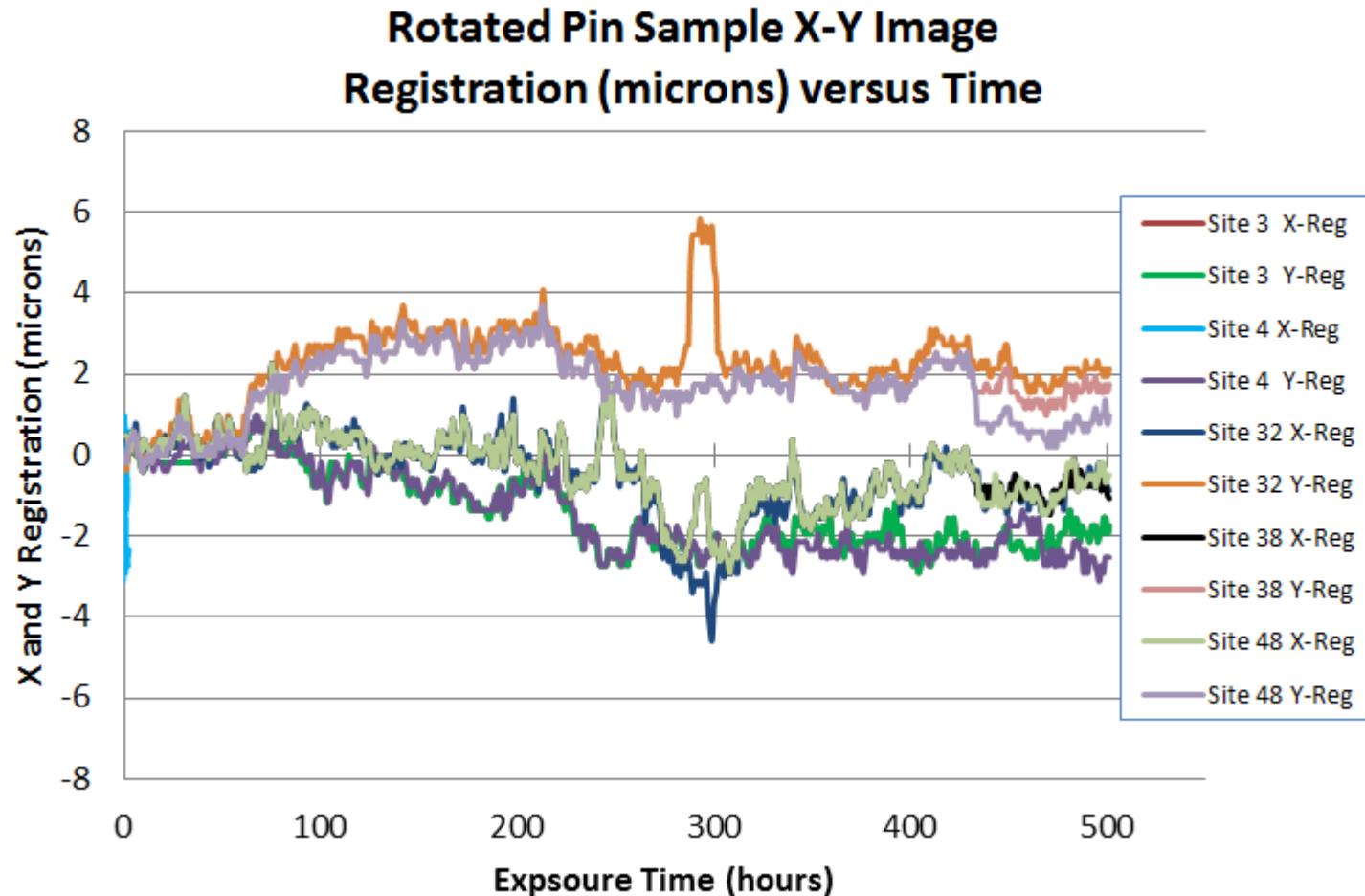
Environmental Control via a Traditional Mixed Flowing Gas System



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System Reliability and Robustness



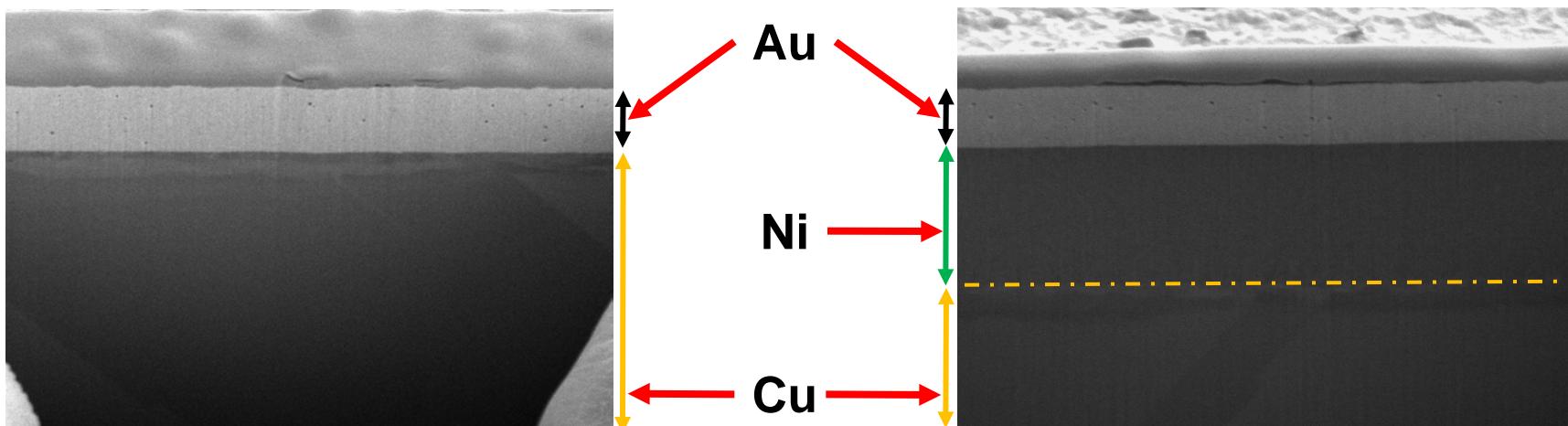
- Monitoring multiple sites over time requires high positional accuracy
 - Accuracy of approximately +/- 5 microns for fully automated operation demonstrated for 500 hrs.
 - Approximately 1,000,000 motorized stages movements occurred during this time period without any faults or requiring any manual intervention





Application to Surveillance Relevant Materials: Atmospheric Corrosion of Connectors

- Material used for microelectronic connectors throughout the stockpile
- Oxygen free copper panels, mechanically lapped to a 15-20nm RMS finish
- Electroplated with one of two metallurgies
 - 2.5 μm Au (ASTM Type I, Code C, class 2.5)
 - 2.5 μm Au over 5 μm Ni



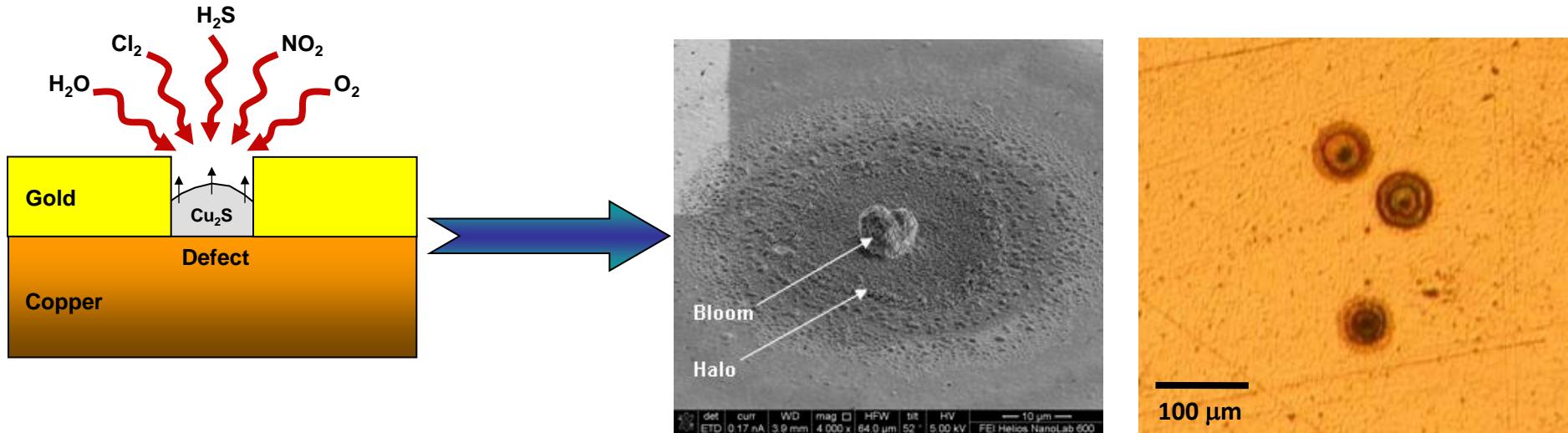
- Models developed for such contacts (e.g., SAND08-5737) depend on accurate measure of corrosion process over time (corrosion site density, size distribution, etc.)



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Corrosion Morphology



- Existing models require precise knowledge of specific aspects of the corrosion process
 - Number density and size distribution of corrosion sites
 - Growth behavior of individual corrosion sites
- Prior investigations (at SNL and in the literature) provide very limited information on the aforementioned quantities.

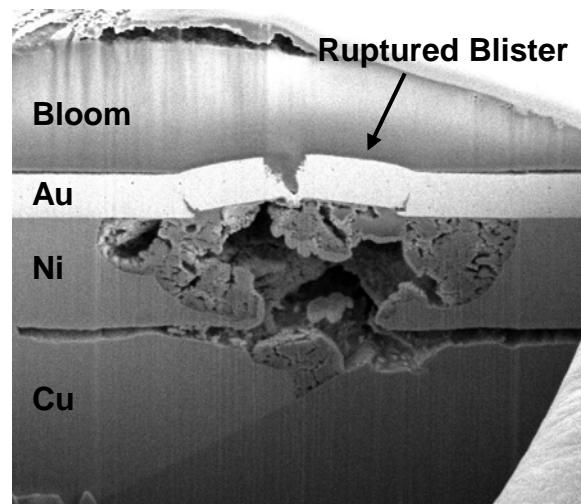
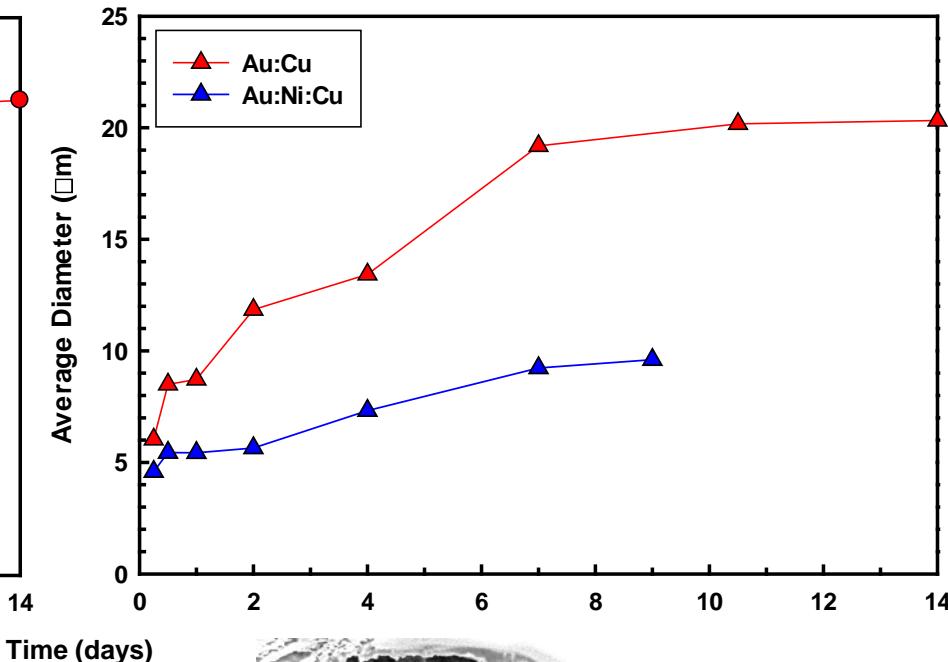
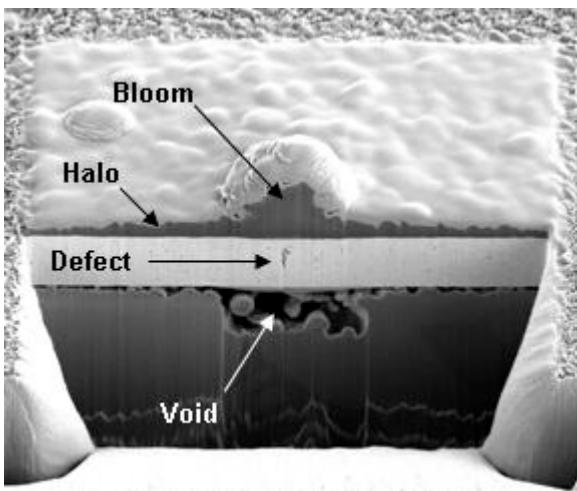
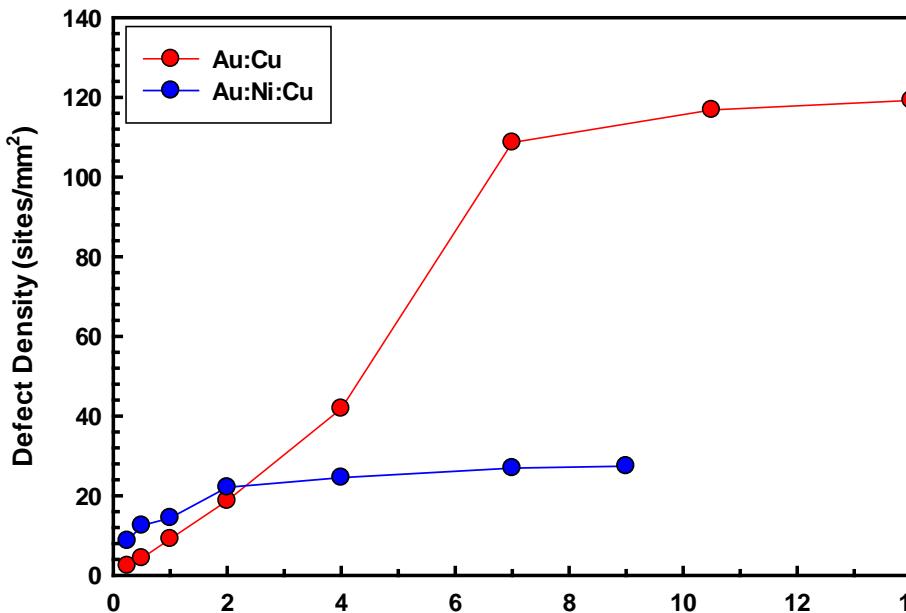


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Image Analysis – Defect Density vs. Time

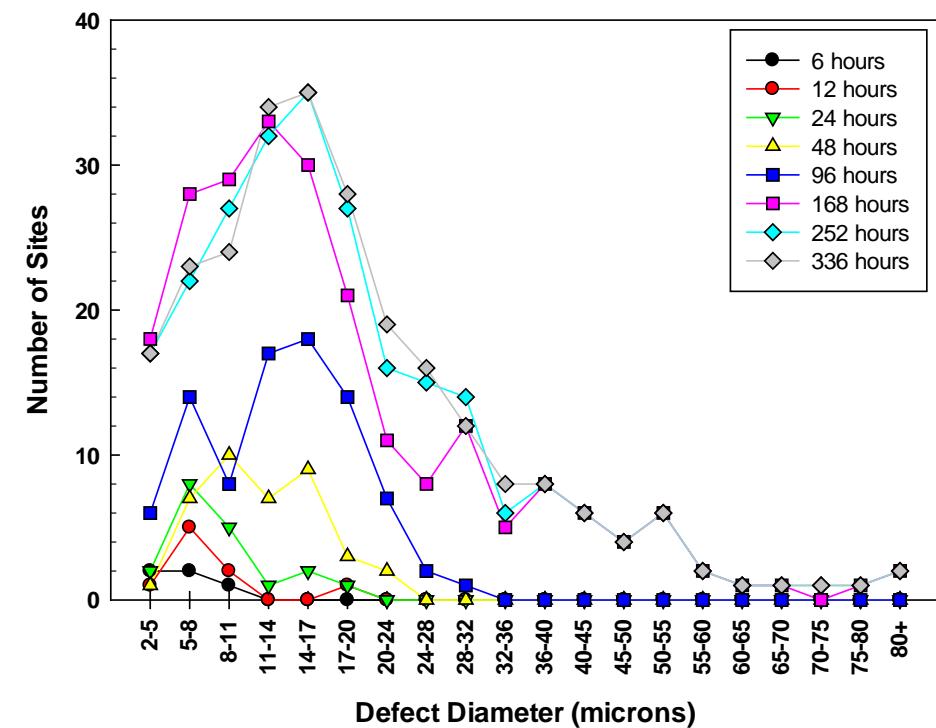
Au:Ni:Cu vs. Au:Cu Samples



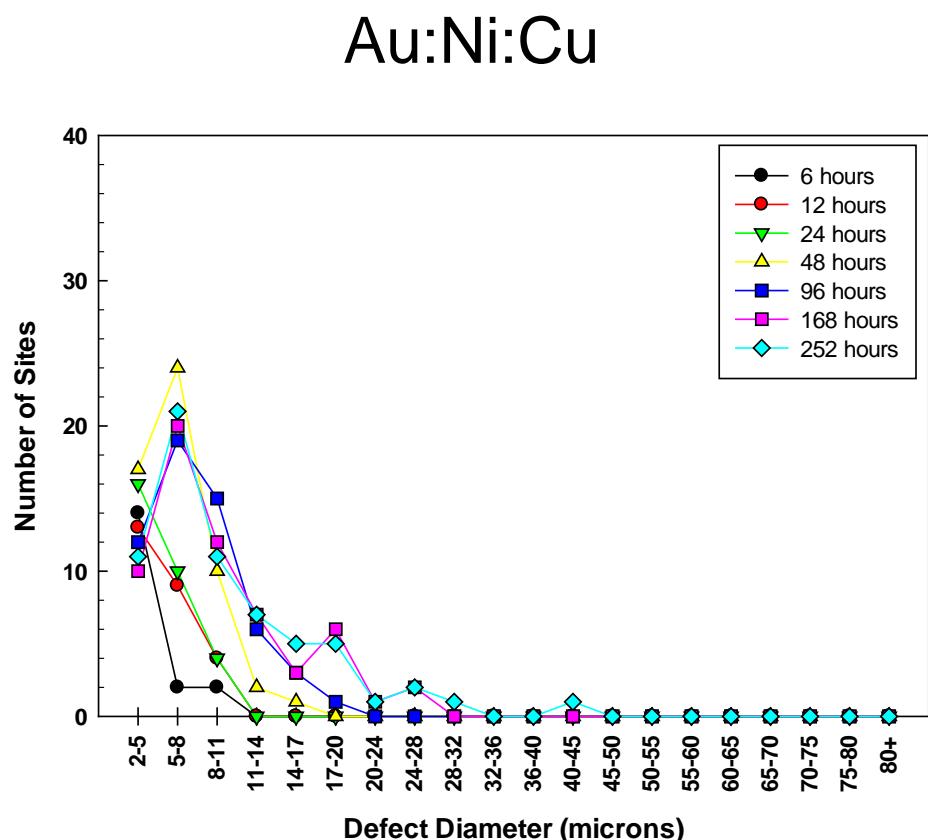
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Image Analysis

Defect Size Distribution vs. Time - Au:Cu vs. Au:Ni:Cu



Au:Cu



Au:Ni:Cu



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Image Analysis on a Planar Surface

Individual Defect Size vs. Time for Au:Ni:Cu Sample

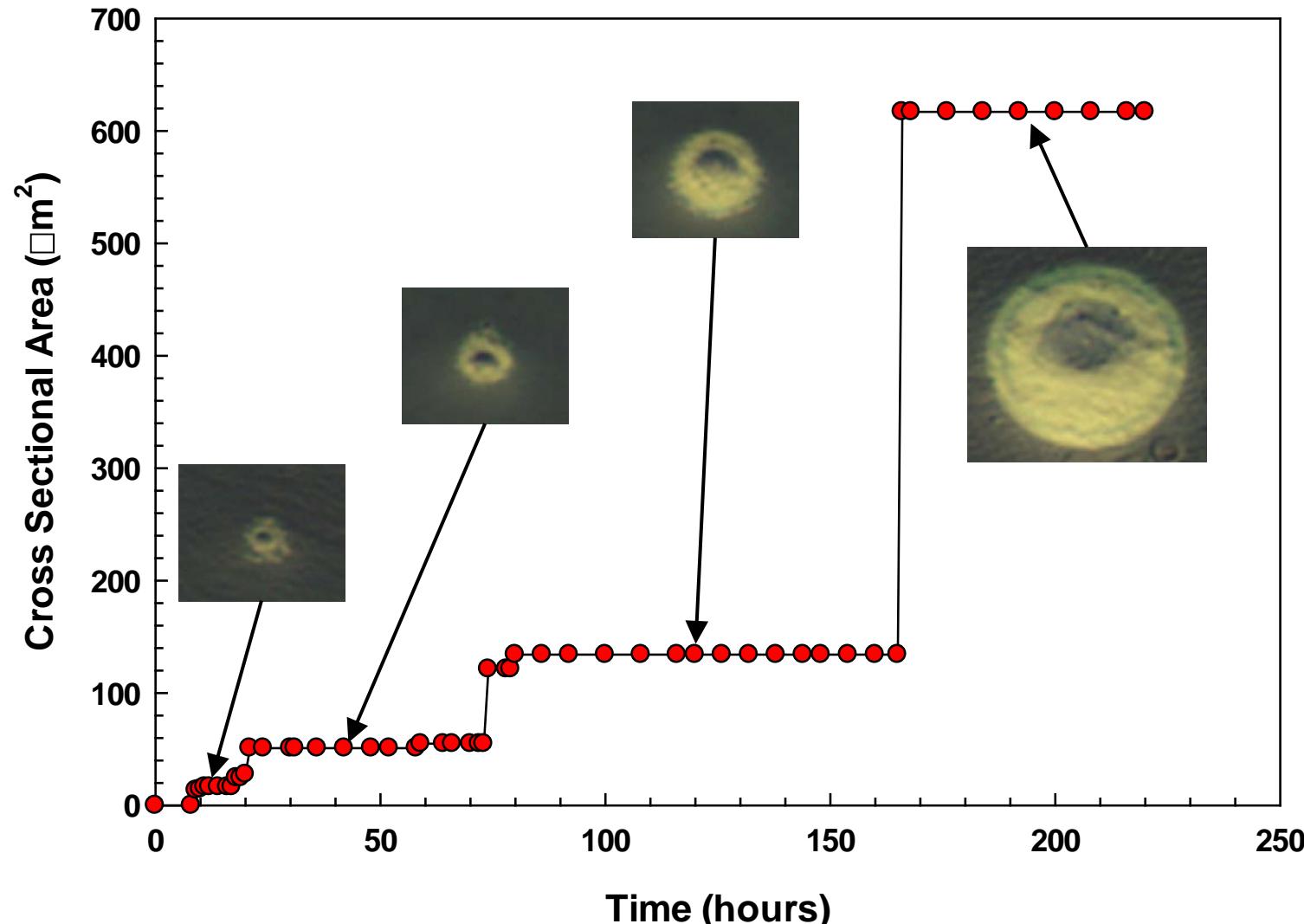
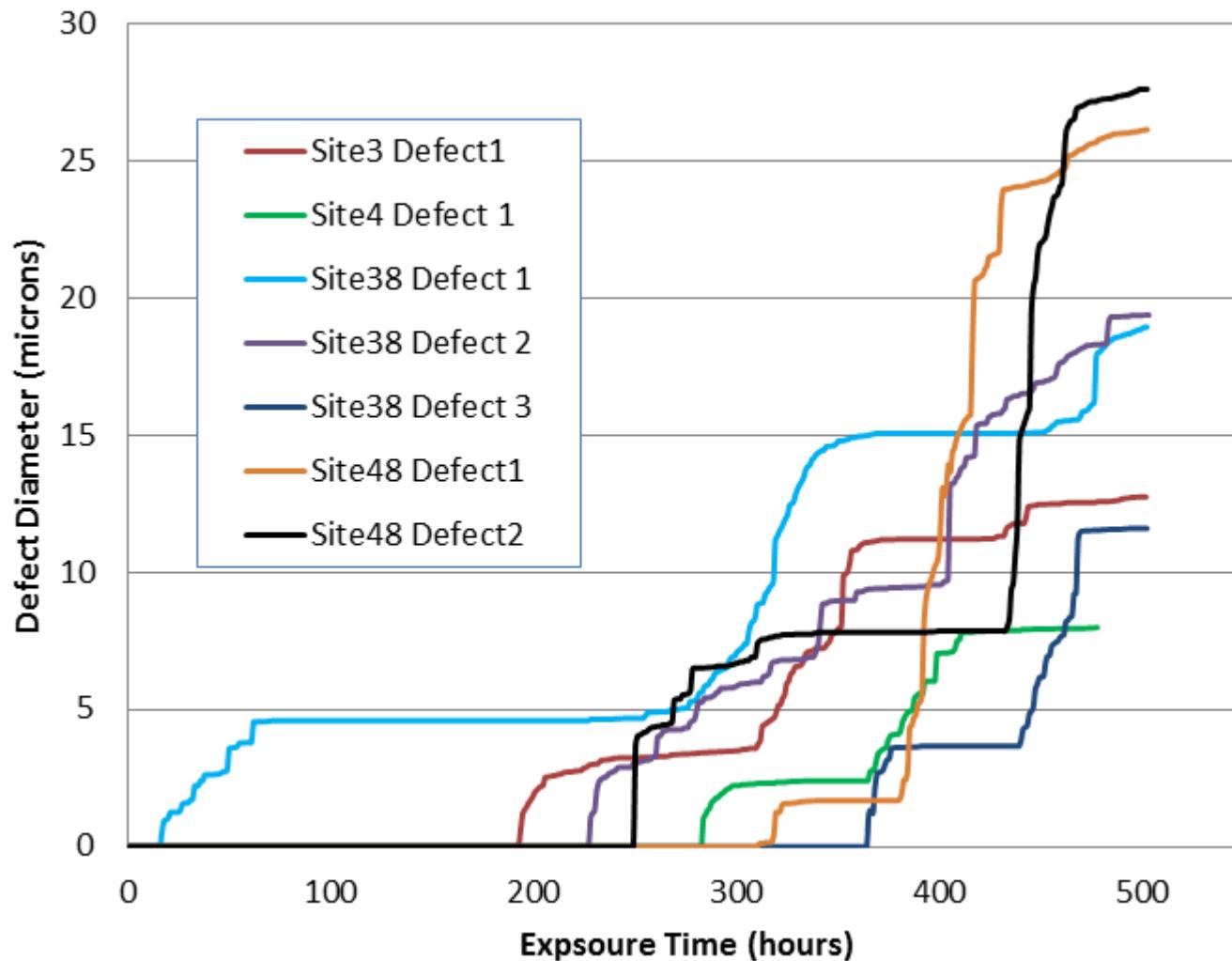




Image Analysis on a Connector Pin

Individual Defect Size vs. Time Connector pin





Summary/Conclusions

- **Differential imaging system has been developed that enables samples undergoing atmospheric corrosion to be imaged in real time**
 - System functionality demonstrated on noble metal plated copper as used in microelectronic connectors
- **System has provided considerable insight into the sulfidation process for noble metal plated copper**
 - Unbiased measure of corrosion site density and size distribution
 - Time dependent evaluation of corrosion site size
 - Multi-stage growth process revealed
 - While additional work is necessary to confirm, experiments to date agree with mechanism proposed (Enos, 2010) for site nucleation, growth, and passivation/stifling



Future Work

- **Development of system project complete after FY13**
 - Documentation
 - Software refinement (continuous)
 - Reliability demonstration
- **Now a viable analysis technique**
 - Allows for customization
 - Provides a non-destructive analysis of surface over time
 - Currently focused on connector degradation (noble metal plated copper and Alloy 52)
 - Combine with techniques such as contact resistance measurement to establish link between degradation and performance

